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|--------------------------|-----------------------------|-------------------------------------|---------------------|
| PCN Number: | 20180914001 | PCN Date: | September 14, 2018 |
| Title: | Datasheet for TPS54320 | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services |
| Change Type: | | | |
| <input type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Design |
| <input type="checkbox"/> | Assembly Process | <input checked="" type="checkbox"/> | Data Sheet |
| <input type="checkbox"/> | Assembly Materials | <input type="checkbox"/> | Part number change |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> | Test Site |
| <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Site |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Material |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Process |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Site |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Materials |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Process |

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TPS54320

SLVS982C – AUGUST 2010 – REVISED APRIL 2018

| Changes from Revision B (November 2014) to Revision C | Page |
|--|------|
| • Added links for WEBENCH and top navigator icon for TI reference design | 1 |
| • Changed "Handling Ratings" to "ESD Ratings"; move Storage temperature to "Abs Max" table | 4 |
| • Changed R _{θJA} from "47.2" to "42.8" °C/W; R _{θJC(top)} from "64.8" to "39.4" °C/W; R _{θJB} from "14.4" to "15.9" °C/W; ψ _{JT} from "0.5" to "0.9" °C/W ; ψ _{JB} from "14.7" to "15.9" °C/W ; R _{θJC(bot)} from "3.2" to "3.9" °C/W | 5 |
| • Changed "I _h = 3.4 μA" to "I _h = 2.25 μA" in Equation 3..... | 14 |
| • Changed "OVP threshold" to "VSENSE falling (Good) threshold of 106%" in last sentence of <i>Output Overvoltage Protection (OVP)</i> | 17 |
| • Corrected pin name from SYNC to RT/CLK in <i>Synchronization (CLK Mode)</i> | 22 |

The datasheet number will be changing.

| | | |
|---------------|--------------|------------|
| Device Family | Change From: | Change To: |
| TPS54320 | SLVS982B | SLVS982C |

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TPS54320>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

| | | | |
|--------------|--------------|--|--|
| TPS54320RHLR | TPS54320RHLL | | |
|--------------|--------------|--|--|

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|--------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |